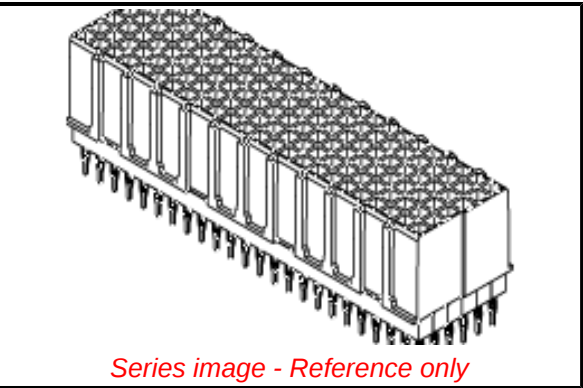


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Part Number: 0737801163
Status: Active
Overview: HDM Backplane Connector System
Description: HDM Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 13.00mm, Pin Length 4.00mm, Solder Tail



Series image - Reference only

Documents:
[3D Model](#)
[Drawing \(PDF\)](#)
[Product Specification PS-73780-999-001 \(PDF\)](#)
[Product Specification TS-73670-990-001 \(PDF\)](#)
[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

UL E29179

General

Product Family Backplane Connectors
Series 73780
Application Daughtercard, Mezzanine
Comments Solder Tail
Component Type PCB Receptacle
Overview HDM Backplane Connector System
Product Name HDM
UPC 800754782241

Physical

Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Copper-Nickel-Tin
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Net Weight 20.030/g
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 4.00mm
PCB Locator No
PCB Retention None
PCB Thickness - Recommended 1.60mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 2.540µm
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55° to +105°C
Termination Interface: Style Through Hole

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Not Contained Per -
ED/61/2018 (27 June
2018)

Halogen-Free

Status

Low-Halogen

Need more information on product
environmental compliance?

Email productcompliance@molex.com
Please visit the [Contact Us](#) section for any
non-product compliance questions.

China ROHS	Not Relevant
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

73780 Series

Mates With

HDM Board-to-Board Backplane Header
73642 , 73643 , 73644 , 73942 , 73943 ,
73944 , 7 4349, 74428. HDM Board-to-
Board Stacking Header 73769 , 73770 ,
73782 , 73783 , 73771

Electrical

Current - Maximum per Contact	15.0A, 1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	005
Lead-freeProcess Capability	WAVE
Max. Cycles at Max. Process Temperature	001
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Product Specification	PS-73780-999-001, TS-73670-990-001
Sales Drawing	SD-73780-004

This document was generated on 09/10/2018

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